

**MOSER
PATTERSON &
SHERIDAN, LLP**

ATTORNEYS AT LAW

3040 Post Oak Blvd, Suite 1500
Houston, TX 77056-6582
TEL 713.621.4844
FAX 713.623.4846
WWW.MPS.LP.COM

Facsimile Cover Sheet

**RECEIVED
CENTRAL FAX CENTER
JUN 01 2004**

OFFICIAL

DATE: June 1, 2004
FILE NO.: AMAT/5262/CMP/CMP/RKK
TO: Examiner Edna Wong
FAX NO.: 571-273-1349
PHONE NO.: 571-272-1349
COMPANY: USPTO
FROM: Keith M. Tackett
PAGE(S) with cover: 2
ORIGINAL TO FOLLOW? YES NO

SECOND RESPONSE TO FINAL OFFICE ACTION DATED FEBRUARY 6, 2004

TITLE: Method and Apparatus For Forming Metal Layers
U.S. SERIAL NO.: 09/961,134
FILING DATE: September 21, 2001
INVENTOR: Tsai, et al.
EXAMINER: Edna Wong
GROUP ART UNIT: 1753
CONFIRMATION NO.: 4110

CONFIDENTIALITY NOTE

The document accompanying this facsimile transmission contains information from the law firm of Moser, Patterson & Sheridan, LLP, which is confidential or privileged. The information is intended to be for the use of the individual or entity named on this transmission sheet. If you are not the intended recipient, be aware that any disclosure, copying, distribution or use of the contents of this faxed information is prohibited. If you have received this facsimile in error, please notify us by telephone immediately so that we can arrange for the retrieval of the original documents at no cost to you.

275260_1

IN THE CLAIMS:

The status of the claims is as follows:

1-23. (Cancelled)

24. (Previously Presented): A method of forming a metal layer on a substrate, comprising:

positioning a substrate in an electroplating cell having a porous pad and an electrolyte solution therein;

contacting at least a portion of the substrate to the porous pad;

forming a metal layer on the substrate by biasing the substrate relative to an electrode at a first electrical bias and then biasing the substrate relative to the electrode at a second electrical bias, wherein the first electrical bias deposits metal on the substrate and the second electrical bias removes metal from the substrate; and

varying the magnitude of the second electrical bias relative to the first electrical bias as the metal layer is formed.

25. (Cancelled)

RECEIVED
CENTRAL FAX CENTER

JUN 01 2004

OFFICIAL